

TLP2312

1. Applications

- Programmable Logic Controllers (PLCs)
- Industrial Inverters
- High-Speed Digital Interfacing for Instrumentation and Control Devices

2. General

TLP2312 is 5 Mbps high speed photocoupler operated at low supply voltage in the small SO6 package.

Since supply voltage of only 2.2 V is needed to operate TLP2312, building another power supply circuit is unnecessary even in using it in a low supply voltage system of 2.5 V LVCMOS level. Therefore, this product contributes to reduce the number of components.

The low threshold input current (I_{FLH}) of 1.6 mA (max) and the low supply current (I_{DDL}/I_{DDH}) of 0.5 mA (max) at entire operating temperature range of -40 °C to 125 °C enables TLP2312 to be driven from a microcontroller directly, and provides energy saving of systems.

The detector has a totem-pole output stage with current sourcing and sinking capabilities. TLP2312 has an internal Faraday shield that provides a guaranteed common-mode transient immunity of ± 20 kV/ μ s.

3. Features

- (1) Package: SO6
- (2) Data transfer rate: 5 Mbps (typ.)
- (3) Supply current: 0.5 mA (max)
- (4) Threshold input current: 1.6 mA (max)
- (5) Supply voltage: 2.2 to 5.5 V
- (6) Operating temperature range: -40 to 125 °C
- (7) Pulse width distortion: 20 ns (max)
- (8) Isolation voltage: 3750 Vrms (min)
- (9) Safety standards

UL-recognized: UL 1577, File No.E67349

cUL-recognized: CSA Component Acceptance Service No.5A File No.E67349

VDE-approved: EN 60747-5-5, EN 62368-1 (**Note 1**)

CQC-approved: GB4943.1, GB8898 Japan Factory (Pending)



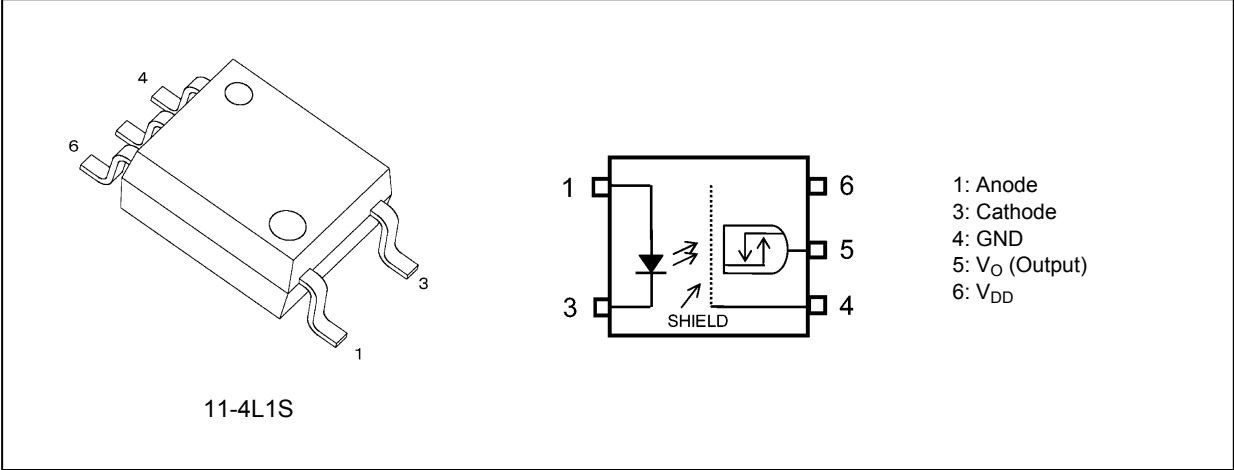
仅适用于海拔 2000m 以下地区安全使用

Note 1: When a VDE approved type is needed, please designate the **Option (V4)**.

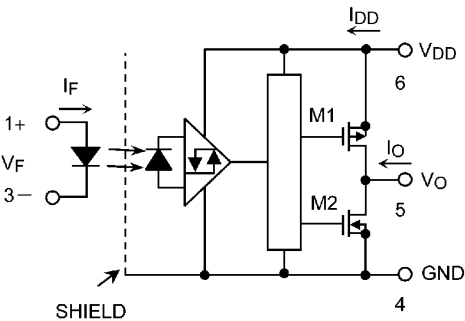
Start of commercial production

2020-02

4. Packaging and Pin Assignment



5. Internal Circuit (Note)



Note: A 0.1-μF bypass capacitor must be connected between pin 6 and pin 4.

6. Principle of Operation

6.1. Truth Table

| Input | LED | Output |
|-------|-----|--------|
| H | ON | H |
| L | OFF | L |

6.2. Mechanical Parameters

| Characteristics | Min | Unit |
|------------------------------|-----|------|
| Creepage distances | 5.0 | mm |
| Clearance | 5.0 | |
| Internal isolation thickness | 0.4 | |

7. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$)

| | Characteristics | Symbol | Note | Rating | Unit |
|----------|--|-------------------------------|----------|------------------------|------------------------|
| LED | Input forward current | I_F | | 8 | mA |
| | Input forward current derating ($T_a \geq 110\text{ }^{\circ}\text{C}$) | $\Delta I_F / \Delta T_a$ | | -0.32 | mA/ $^{\circ}\text{C}$ |
| | Input forward current (pulsed) | I_{FP} | (Note 1) | 16 | mA |
| | Input forward current derating (pulsed) ($T_a \geq 110\text{ }^{\circ}\text{C}$) | $\Delta I_{FP} / \Delta T_a$ | | -0.64 | mA/ $^{\circ}\text{C}$ |
| | Peak transient input forward current | I_{FPT} | (Note 2) | 1 | A |
| | Peak transient input forward current derating ($T_a \geq 110\text{ }^{\circ}\text{C}$) | $\Delta I_{FPT} / \Delta T_a$ | | -40 | mA/ $^{\circ}\text{C}$ |
| | Input reverse voltage | V_R | | 5 | V |
| | Input power dissipation | P_D | | 20 | mW |
| | Input power dissipation derating ($T_a \geq 110\text{ }^{\circ}\text{C}$) | $\Delta P_D / \Delta T_a$ | | -0.8 | mW/ $^{\circ}\text{C}$ |
| Detector | Output current | I_O | | 8 | mA |
| | Output voltage | V_O | | -0.5 to $V_{DD} + 0.5$ | V |
| | Supply voltage | V_{DD} | | -0.5 to 6 | V |
| | Output power dissipation | P_O | | 20 | mW |
| | Output power dissipation derating ($T_a \geq 110\text{ }^{\circ}\text{C}$) | $\Delta P_O / \Delta T_a$ | | -0.8 | mW/ $^{\circ}\text{C}$ |
| Common | Operating temperature | T_{opr} | | -40 to 125 | $^{\circ}\text{C}$ |
| | Storage temperature | T_{stg} | | -55 to 125 | $^{\circ}\text{C}$ |
| | Lead soldering temperature (10 s) | T_{sol} | | 260 | $^{\circ}\text{C}$ |
| | Isolation voltage (AC, 60 s, R.H. $\leq 60\%$) | BV_S | (Note 3) | 3750 | Vrms |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width (PW) $\leq 1\text{ ms}$, duty = 50 %

Note 2: Pulse width (PW) $\leq 1\text{ }\mu\text{s}$, 300 pps

Note 3: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4, 5 and 6 are shorted together.

8. Recommended Operating Conditions (Note)

| Characteristics | Symbol | Note | Min | Typ. | Max | Unit |
|-------------------------|--------------|----------|-----|---------------|-----|--------------------|
| Input on-state current | $I_{F(ON)}$ | | 2 | — | 6 | mA |
| Input off-state voltage | $V_{F(OFF)}$ | | 0 | — | 0.8 | V |
| Rise time of I_F | $t_{r(IF)}$ | (Note 1) | 5 n | — | 60 | s |
| Fall time of I_F | $t_{f(IF)}$ | (Note 2) | 5 n | — | 60 | s |
| Supply voltage | V_{DD} | (Note 3) | 2.2 | 2.5 / 3.3 / 5 | 5.5 | V |
| Operating temperature | T_{opr} | (Note 3) | -40 | — | 125 | $^{\circ}\text{C}$ |

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this data sheet should also be considered.

Note: A ceramic capacitor (0.1 μF) should be connected between pin 6 and pin 4 to stabilize the operation of a high-gain linear amplifier. Otherwise, this photocoupler may not switch properly. The bypass capacitor should be placed within 1 cm of each pin.

Note 1: The rise time of input forward current which takes for linear increase from 0 mA to 2 mA.

Note 2: The fall time of input forward current which takes for linear decrease from 2 mA to 0 mA.

Note 3: Denotes the operating range, not the recommended operating condition.

9. Electrical Characteristics (Note) (Unless otherwise specified, $T_a = -40$ to $125\text{ }^{\circ}\text{C}$, $V_{DD} = 2.2$ to 5.5 V)

| Characteristics | Symbol | Test Circuit | Test Condition | Min | Typ. | Max | Unit |
|---|---------------------------|--------------|--|-----------------|------------------|------|------------------------|
| Input forward voltage | V_F | | $I_F = 2\text{ mA}$ | 1.2 | — | 1.9 | V |
| | | | $I_F = 2\text{ mA}$, $T_a = 25\text{ }^{\circ}\text{C}$ | 1.4 | 1.53 | 1.7 | |
| Input forward voltage temperature coefficient | $\Delta V_F / \Delta T_a$ | | $I_F = 2\text{ mA}$ | — | -1.58 | — | mV/ $^{\circ}\text{C}$ |
| Input reverse current | I_R | | $V_R = 5\text{ V}$, $T_a = 25\text{ }^{\circ}\text{C}$ | — | — | 10 | μA |
| Input capacitance | C_t | | $V = 0\text{ V}$, $f = 1\text{ MHz}$, $T_a = 25\text{ }^{\circ}\text{C}$ | — | 22 | — | pF |
| Low-level output voltage | V_{OL} | Fig. 12.1.1 | $I_O = 20\text{ }\mu\text{A}$, $I_F = 0\text{ mA}$ | — | 0.0008 | 0.1 | V |
| | | | $I_O = 3.2\text{ mA}$, $I_F = 0\text{ mA}$ | — | 0.11 | 0.41 | |
| High-level output voltage | V_{OH} | Fig. 12.1.2 | $I_O = -20\text{ }\mu\text{A}$, $I_F = 2\text{ mA}$ | $V_{DD} - 0.1$ | $V_{DD} - 0.001$ | — | |
| | | | $I_O = -3.2\text{ mA}$, $I_F = 2\text{ mA}$ | $V_{DD} - 0.65$ | $V_{DD} - 0.14$ | — | |
| Low-level supply current | I_{DDL} | Fig. 12.1.3 | $I_F = 0\text{ mA}$ | — | 0.39 | 0.5 | mA |
| High-level supply current | I_{DDH} | Fig. 12.1.4 | $I_F = 2\text{ mA}$ | — | 0.35 | 0.5 | |
| Threshold input current (L/H) | I_{FLH} | | $I_O = -3.2\text{ mA}$, $V_O > V_{DD} - 1\text{ V}$ | — | 0.55 | 1.6 | |

Note: All typical values are at $V_{DD} = 3.3\text{ V}$, $T_a = 25\text{ }^{\circ}\text{C}$, unless otherwise noted.

10. Isolation Characteristics (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$)

| Characteristics | Symbol | Note | Test Condition | Min | Typ. | Max | Unit |
|-------------------------------------|--------|----------|---|-----------|-----------|-----|----------|
| Total capacitance (input to output) | C_S | (Note 1) | $V_S = 0\text{ V}$, $f = 1\text{ MHz}$ | — | 0.8 | — | pF |
| Isolation resistance | R_S | (Note 1) | $V_S = 500\text{ V}$, R.H. $\leq 60\%$ | 10^{12} | 10^{14} | — | Ω |
| Isolation voltage | BV_S | (Note 1) | AC, 60 s | 3750 | — | — | Vrms |

Note 1: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4, 5 and 6 are shorted together.

11. Switching Characteristics (Note)

(Unless otherwise specified, $T_a = -40$ to 125 °C, $V_{DD} = 2.2$ to 5.5 V)

| Characteristics | Symbol | Note | Test Circuit | Test Condition | Min | Typ. | Max | Unit |
|---|------------------------------------|--------------------|--------------|---|--|------|-----|-------|
| Propagation delay time (L/H) | t _{pLH} | (Note 1) | Fig. 12.1.5 | V _{IN} = 2.5 V R _{IN} = 470 Ω C _{IN} = 68 pF | — | 26.8 | 250 | ns |
| Propagation delay time (H/L) | t _{pHL} | | | | — | 27.3 | 250 | |
| Pulse width distortion | t _{pHL} -t _{pLH} | | | | — | 0.5 | 20 | |
| Propagation delay skew (device to device) | t _{psk} | (Note 1), (Note 2) | | | -40 | — | 40 | |
| Propagation delay time (L/H) | t _{pLH} | (Note 1) | | V _{IN} = 3.3 V R _{IN} = 1 kΩ C _{IN} = 22 pF | — | 32.7 | 250 | |
| Propagation delay time (H/L) | t _{pHL} | | | | — | 28.2 | 250 | |
| Pulse width distortion | t _{pHL} -t _{pLH} | | | | — | 4.5 | 20 | |
| Propagation delay skew (device to device) | t _{psk} | (Note 1), (Note 2) | | | -45 | — | 45 | |
| Propagation delay time (L/H) | t _{pLH} | (Note 1) | | V _{IN} = 5 V R _{IN} = 2.2 kΩ C _{IN} = 10 pF | — | 31.3 | 250 | |
| Propagation delay time (H/L) | t _{pHL} | | | | — | 28.5 | 250 | |
| Pulse width distortion | t _{pHL} -t _{pLH} | | | | — | 2.8 | 20 | |
| Propagation delay skew (device to device) | t _{psk} | (Note 1), (Note 2) | | | -45 | — | 45 | |
| Rise time | t _r | (Note 1) | | V _{IN} = 0 → 3.3 V, R _{IN} = 1 kΩ, C _{IN} = 22 pF | — | 2.2 | — | |
| Fall time | t _f | | | | V _{IN} = 3.3 → 0 V, R _{IN} = 1 kΩ, C _{IN} = 22 pF | — | 1.6 | |
| High-level common-mode transient immunity | CM _H | | Fig. 12.1.6 | I _F = 2 mA, V _{CM} = 1000 V _{p-p} , T _a = 25 °C | ±20 | ±40 | — | kV/μs |
| Low-level common-mode transient immunity | CM _L | | | I _F = 0 mA, V _{CM} = 1000 V _{p-p} , T _a = 25 °C | ±20 | ±40 | — | kV/μs |

Note: All typical values are at $V_{DD} = 3.3$ V, $T_a = 25$ °C, unless otherwise noted.

Note 1: $f = 2.5$ MHz, duty = 50 %, input current $t_r = t_f = 5$ ns or less.

Note 2: The propagation delay skew, t_{psk} , is equal to the magnitude of the worst-case difference in t_{pHL} and/or t_{pLH} that will be seen between units at the same given conditions (supply voltage, input current, temperature, etc).

12. Test Circuits and Characteristics Curves

12.1. Test Circuits

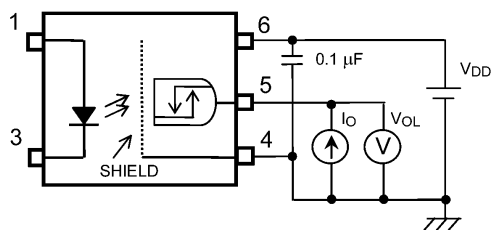


Fig. 12.1.1 V_{OL} Test Circuit

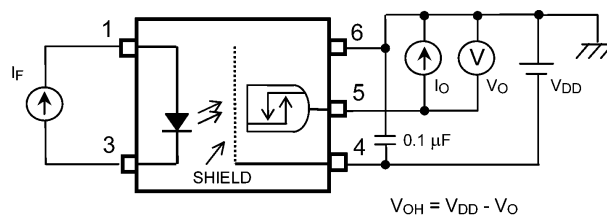


Fig. 12.1.2 V_{OH} Test Circuit

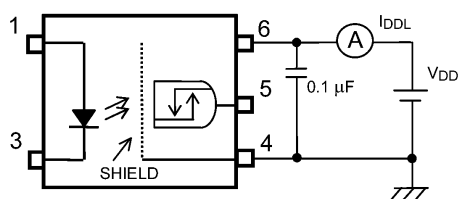


Fig. 12.1.3 I_{DDL} Test Circuit

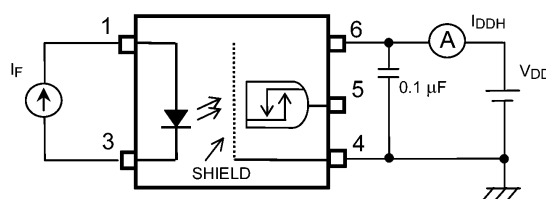
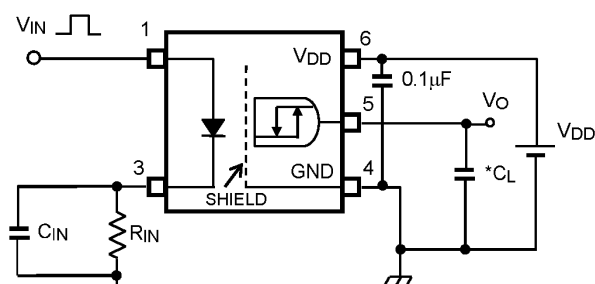


Fig. 12.1.4 I_{DDH} Test Circuit

$V_{IN} = 2.5 \text{ V} / 3.3 \text{ V} / 5 \text{ V}$ (P.G.)

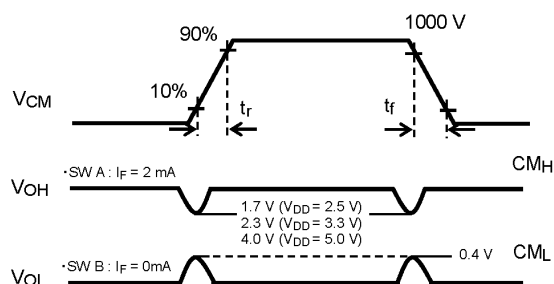
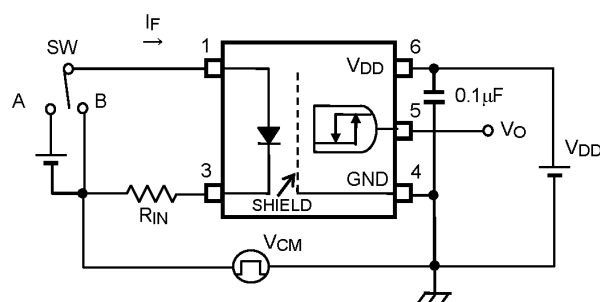
($f = 2.5 \text{ MHz}$, duty = 50 %, less than $t_r = t_f = 5 \text{ ns}$)



P.G.: Pulse generator

* C_L is less than 15 pF which includes probe and stray wiring capacitance.

Fig. 12.1.5 Switching Time Test Circuit and Waveform



$$CM_H = \frac{800(V)}{tr(\mu s)}, \frac{-800(V)}{tf(\mu s)}$$

$$CM_L = \frac{800(V)}{tr(\mu s)}, \frac{-800(V)}{tf(\mu s)}$$

Fig. 12.1.6 Common-Mode Transient Immunity Test Circuit and Waveform

12.2. Characteristics Curves (Note)

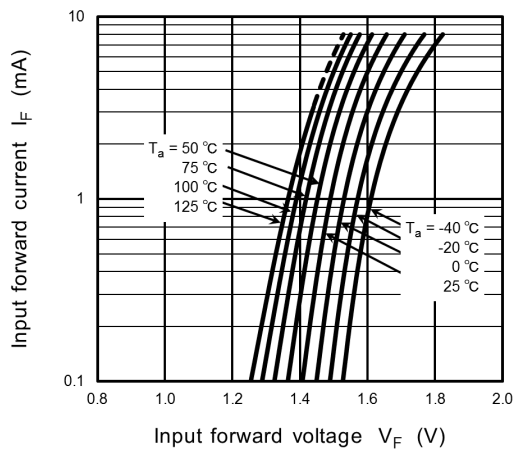


Fig. 12.2.1 $I_F - V_F$

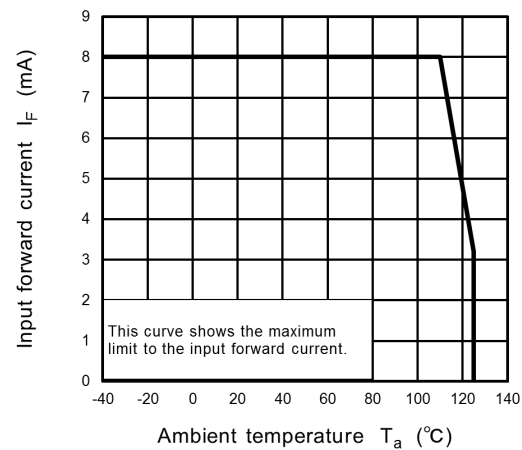


Fig. 12.2.2 $I_F - T_a$

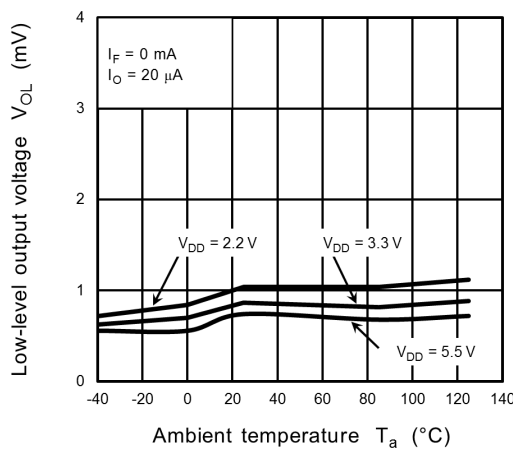


Fig. 12.2.3 $V_{OL} - T_a$

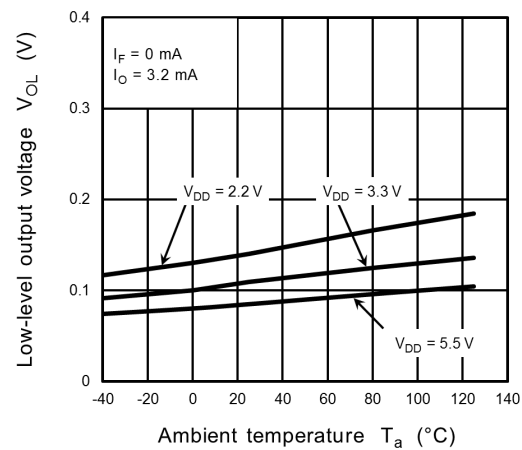


Fig. 12.2.4 $V_{OL} - T_a$

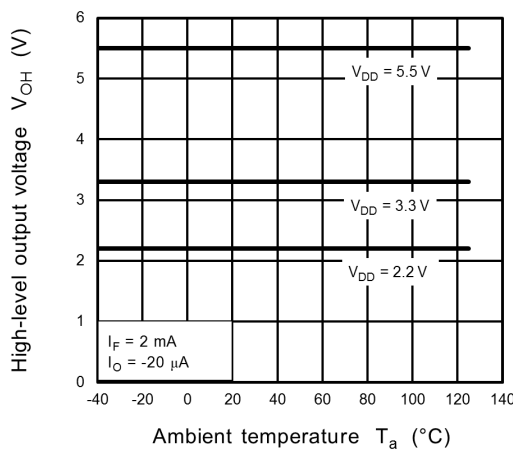


Fig. 12.2.5 $V_{OH} - T_a$

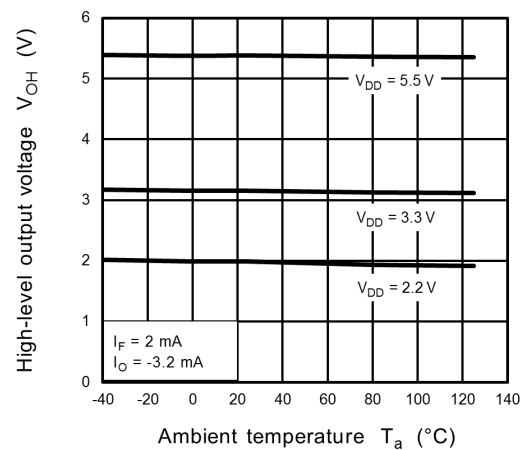


Fig. 12.2.6 $V_{OH} - T_a$

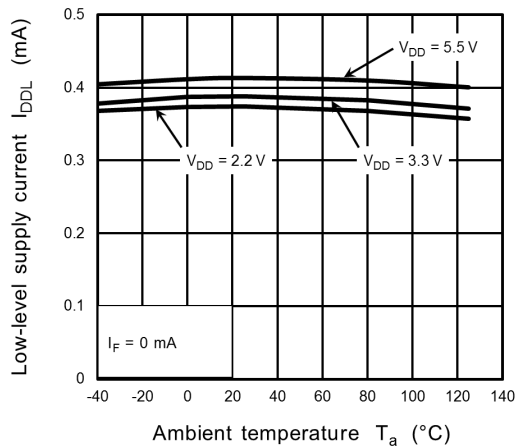


Fig. 12.2.7 $I_{DDL} - T_a$

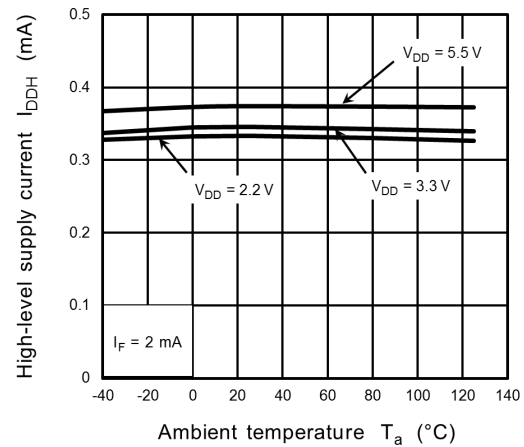


Fig. 12.2.8 $I_{DDH} - T_a$

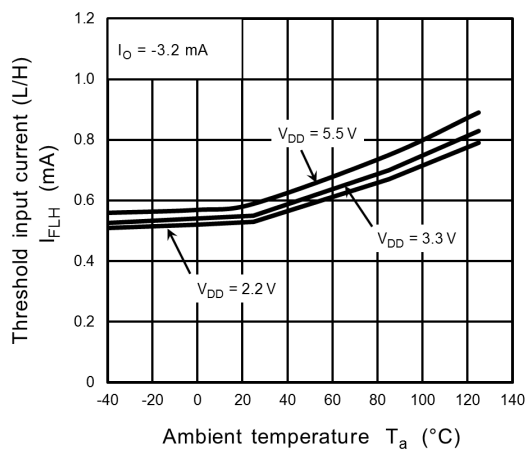


Fig. 12.2.9 $I_{FLH} - T_a$

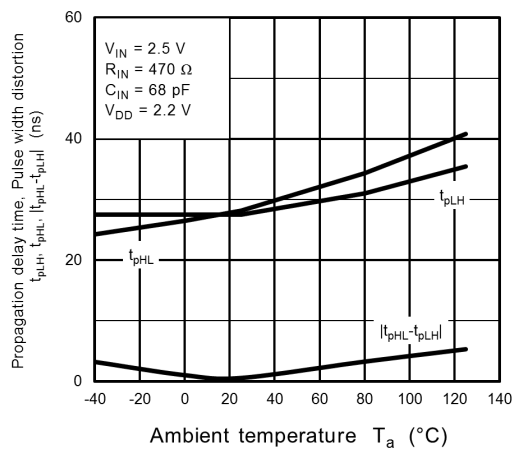


Fig. 12.2.10 t_{pHL} , t_{pLH} , $|t_{pHL} - t_{pLH}| - T_a$

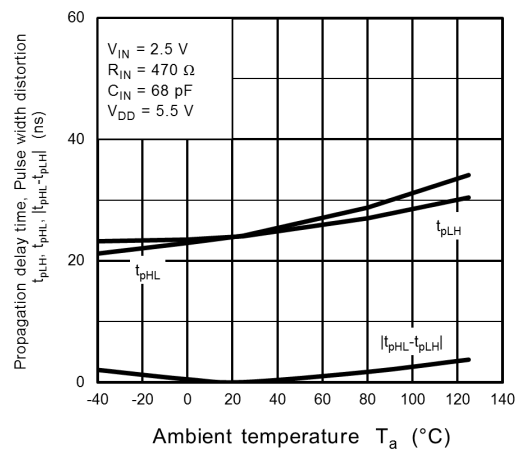


Fig. 12.2.11 t_{pHL} , t_{pLH} , $|t_{pHL} - t_{pLH}| - T_a$

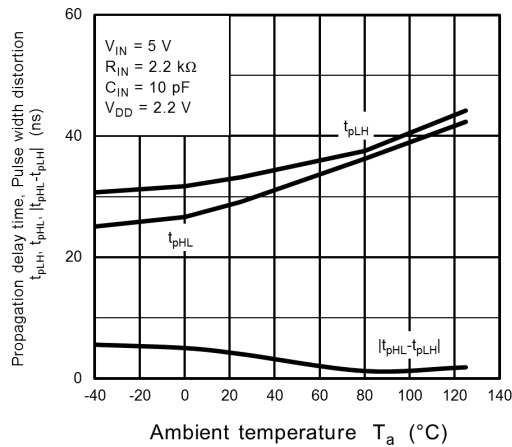


Fig. 12.2.12 t_{pHL} , t_{pLH} , $|t_{pHL} - t_{pLH}|$ - T_a

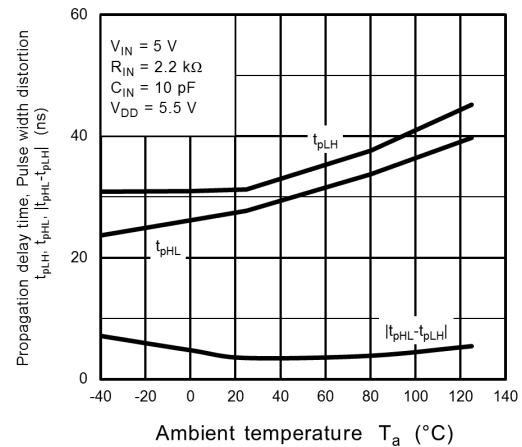


Fig. 12.2.13 t_{pHL} , t_{pLH} , $|t_{pHL} - t_{pLH}|$ - T_a

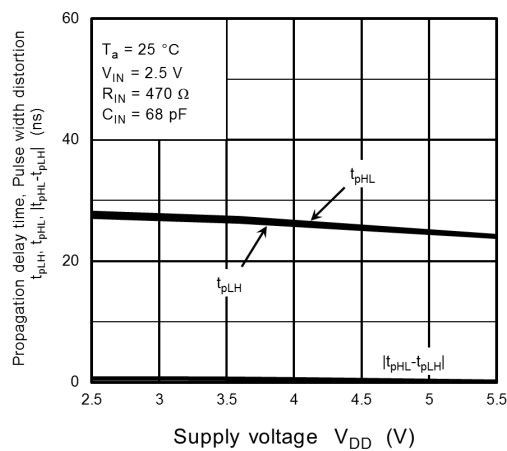


Fig. 12.2.14 t_{pHL} , t_{pLH} , $|t_{pHL} - t_{pLH}|$ - V_{DD}

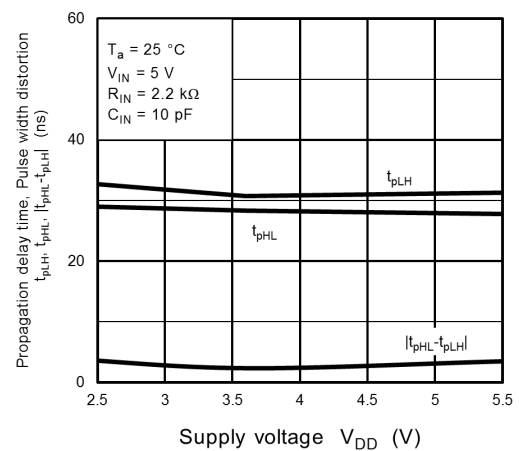


Fig. 12.2.15 t_{pHL} , t_{pLH} , $|t_{pHL} - t_{pLH}|$ - V_{DD}

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

13. Soldering and Storage

13.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

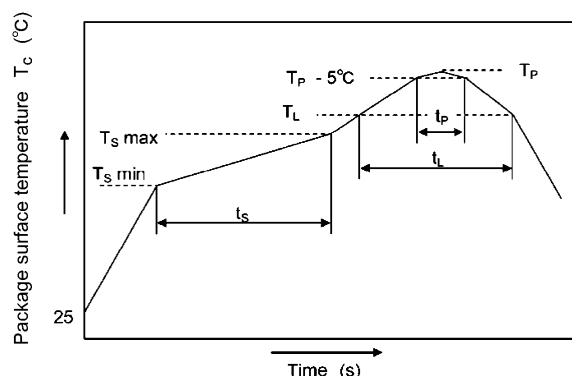
- When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



| | Symbol | Min | Max | Unit |
|--|--------|-----|-----|------|
| Preheat temperature | T_S | 150 | 200 | °C |
| Preheat time | t_S | 60 | 120 | s |
| Ramp-up rate (T_L to T_P) | | | 3 | °C/s |
| Liquidus temperature | T_L | 217 | | °C |
| Time above T_L | t_L | 60 | 150 | s |
| Peak temperature | T_P | | 260 | °C |
| Time during which T_c is between ($T_P - 5$) and T_P | t_P | | 30 | s |
| Ramp-down rate (T_P to T_L) | | | 6 | °C/s |

An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

- When using soldering flow

Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds.

Mounting condition of 260 °C within 10 seconds is recommended.

Flow soldering must be performed once.

- When using soldering Iron

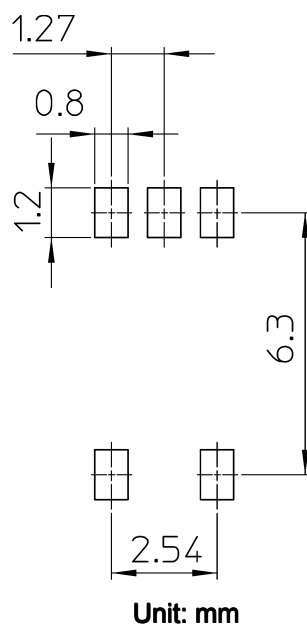
Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C

Heating by soldering iron must be done only once per lead.

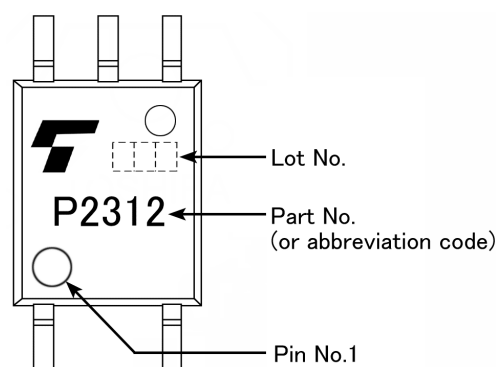
13.2. Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

14. Land Pattern Dimensions (for reference only)



15. Marking



16. EN 60747-5-5 Option (V4) Specification

- Part number: TLP2312 (Note 1)
- The following part naming conventions are used for the devices that have been qualified according to option (V4) of EN 60747.

Example: TLP2312(V4-TPL,E

V4: EN 60747 option

TPL: Tape type

E: [[G]]/RoHS COMPATIBLE (Note 2)

Note 1: Use TOSHIBA standard type number for safety standard application.

e.g., TLP2312(V4-TPL,E → TLP2312

Note 2: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

| Description | Symbol | Rating | Unit |
|---|------------|---|----------|
| Application classification | | | — |
| for rated mains voltage ≤ 150 Vrms | | I-IV | |
| for rated mains voltage ≤ 300 Vrms | | I-III | |
| Climatic classification | | 40 / 125 / 21 | — |
| Pollution degree | | 2 | — |
| Maximum operating insulation voltage | V_{IORM} | 707 | Vpeak |
| Input to output test voltage, Method A $V_{pr} = 1.6 \times V_{IORM}$, type and sample test $t_p = 10$ s, partial discharge < 5 pC | V_{pr} | 1131 | Vpeak |
| Input to output test voltage, Method B $V_{pr} = 1.875 \times V_{IORM}$, 100 % production test $t_p = 1$ s, partial discharge < 5 pC | V_{pr} | 1325 | Vpeak |
| Highest permissible overvoltage (transient overvoltage, $t_{pr} = 60$ s) | V_{TR} | 6000 | Vpeak |
| Safety limiting values (max. permissible ratings in case of fault, also refer to thermal derating curve) | | | |
| current (input current I_F , $P_{SO} = 0$) | I_{Si} | 250 | mA |
| power (output or total power dissipation) | P_{SO} | 400 | mW |
| temperature | T_s | 150 | °C |
| Insulation resistance $V_{IO} = 500$ V, $T_a = 25$ °C $V_{IO} = 500$ V, $T_a = 100$ °C $V_{IO} = 500$ V, $T_a = T_s$ | R_{Si} | $\geq 10^{12}$ $\geq 10^{11}$ $\geq 10^9$ | Ω |

Fig. 16.1 EN 60747 Insulation Characteristics

Table Insulation Related Specifications (Note)

| Insulation Related Parameters | Symbol | TLP2312 |
|-------------------------------|--------|---------|
| Minimum creepage distance | Cr | 5.0 mm |
| Minimum clearance | Cl | 5.0 mm |
| Minimum insulation thickness | ti | 0.4 mm |
| Comparative tracking index | CTI | 500 |

Note: This photocoupler is suitable for **safe electrical isolation** only within the safety limit data.
 Maintenance of the safety data shall be ensured by means of protective circuits.



Fig. 16.2 Marking on Packing for EN 60747

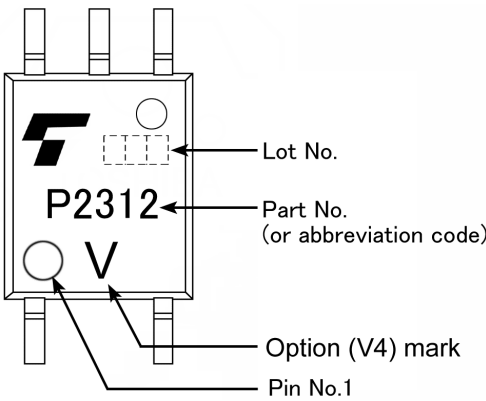


Fig. 16.3 Marking Example (Note)

Note: A different marking is used for photocouplers that have been qualified according to option (V4) of EN 60747.
 See Fig.16.3.

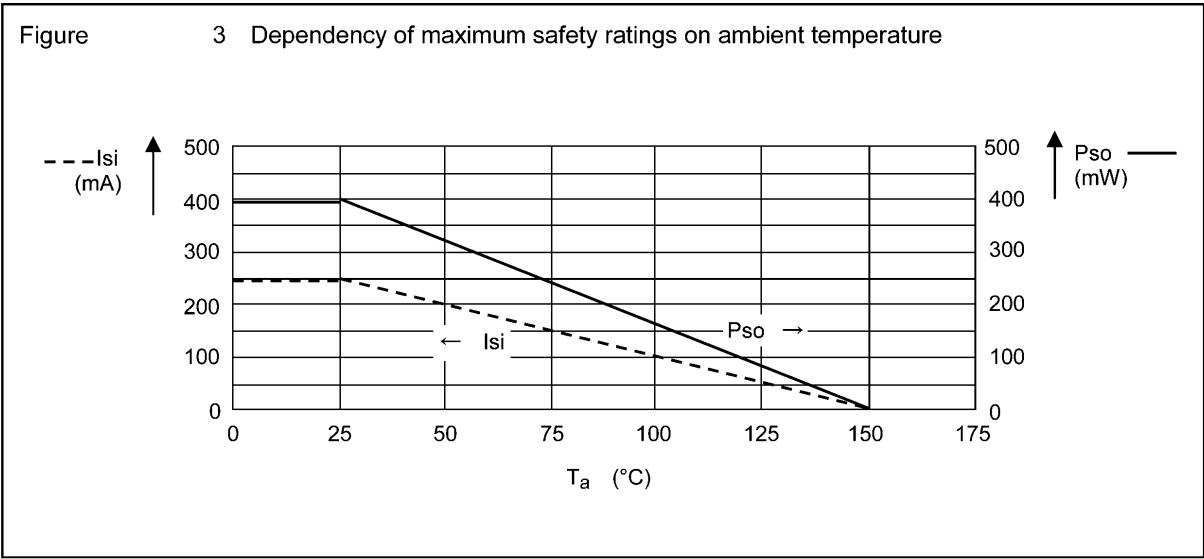
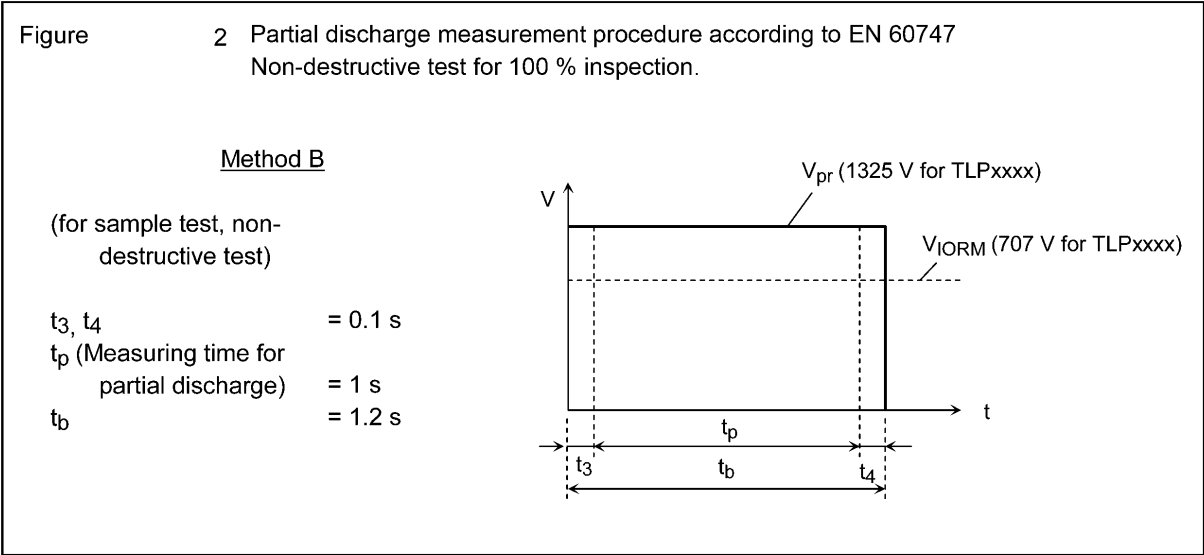
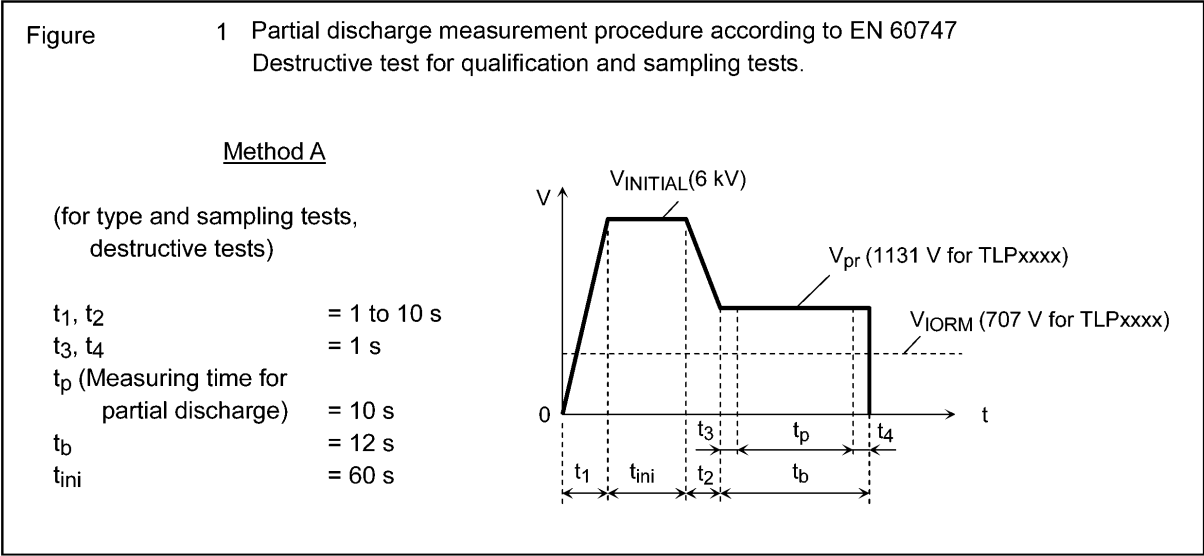


Fig. 16.4 Measurement Procedure

17. Ordering Information

When placing an order, please specify the part number, tape type and quantity as shown in the following example.

Example) TLP2312(TPL,E 3000 pcs

Part number: TLP2312

Tape type: TPL

[[G]]/RoHS COMPATIBLE: E (**Note 1**)

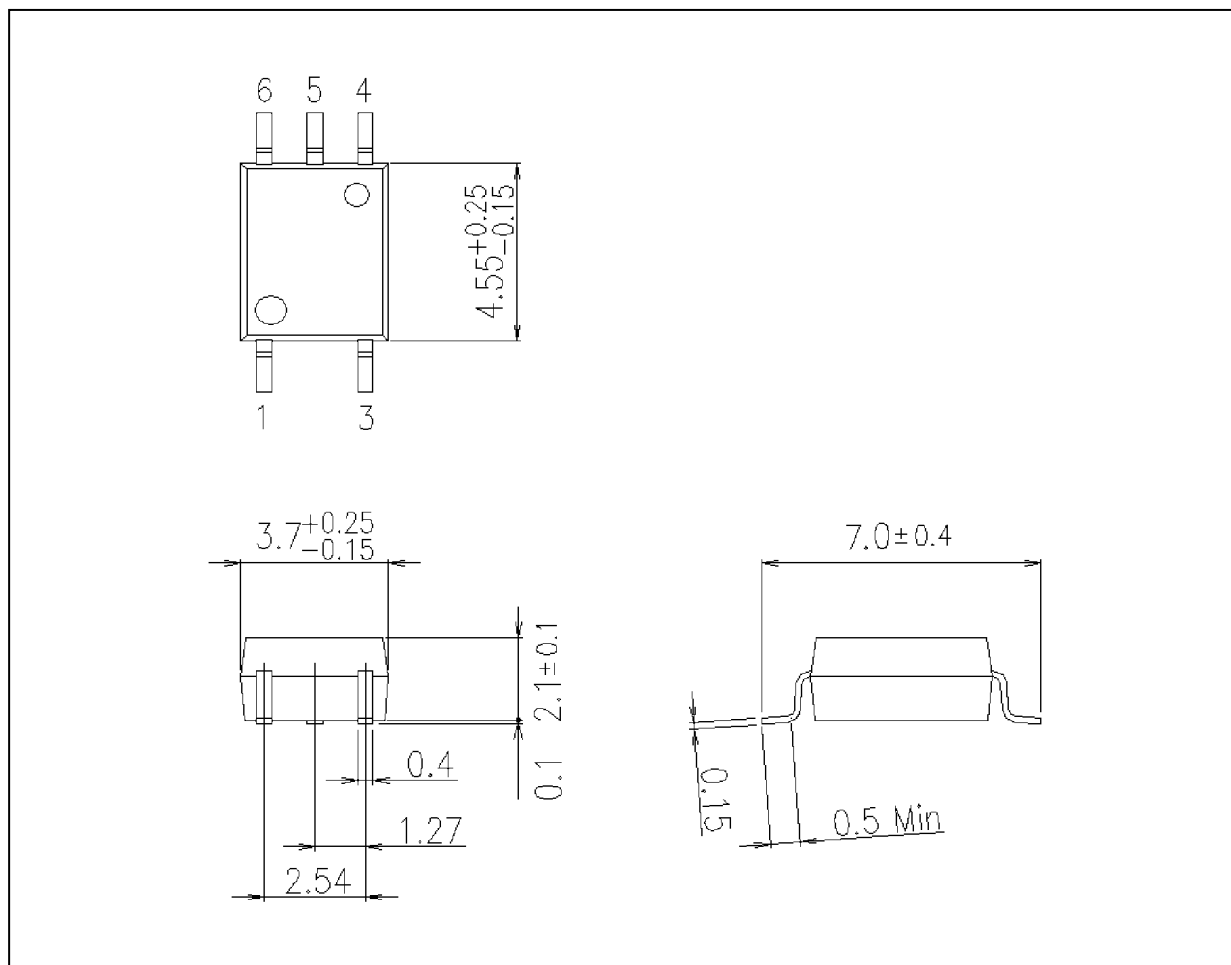
Quantity (must be a multiple of 3000): 3000 pcs

Note 1: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Package Dimensions

Unit: mm



Weight: 0.08 g (typ.)

| Package Name(s) |
|------------------|
| TOSHIBA: 11-4L1S |

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